



SOT556-1

plastic shrink small outline package; 24 leads; body width 3.9 mm; lead pitch 0.635 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP24
Package type industry code	SSOP24
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-137
Mounting method type	S (surface mount)
Issue date	18-2-2003

Table 1. Package summary

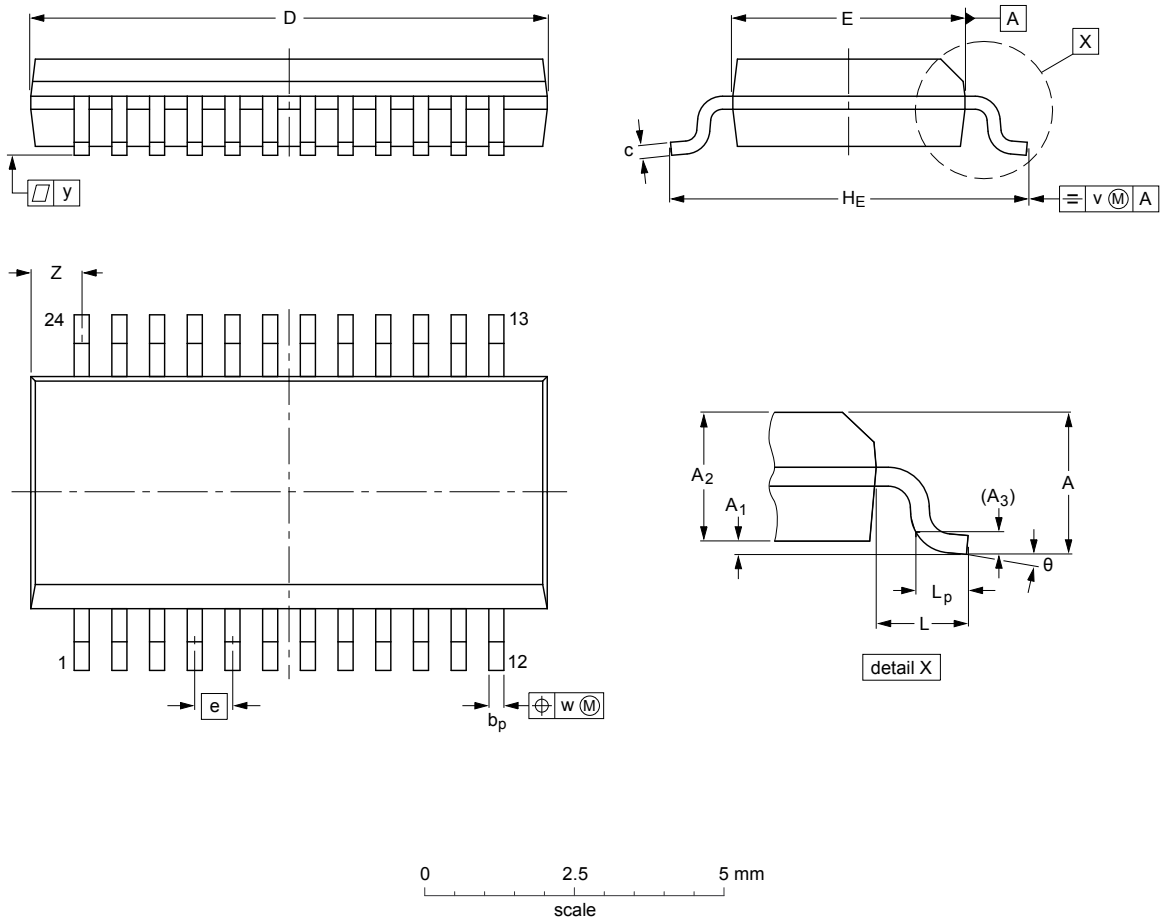
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.6	-	8.7	8.8	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	[tbd]	-	1.73	1.73	mm
A ₂	package height	1.4	-	1.47	1.55	mm
n ₂	actual quantity of termination	-	-	24	-	



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2. Package outline

SSOP24: plastic shrink small outline package; 24 leads; body width 3.9 mm; lead pitch 0.635 mm SOT556-1



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.73	0.25 0.10	1.55 1.40	0.25	0.31 0.20	0.25 0.18	8.8 8.6	4.0 3.8	0.635	6.2 5.8	1	0.89 0.41	0.25	0.18	0.1	1.05 0.66	8° 0°
inches	0.068	0.0098 0.0040	0.061 0.055	0.01	0.012 0.008	0.0098 0.0075	0.344 0.337	0.157 0.150	0.025	0.244 0.228	0.041	0.035 0.016	0.01	0.007	0.004	0.040 0.026	8° 0°

Note

1. Plastic or metal protrusions of 0.2 mm (0.008 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT556-1		MO-137				99-12-27 03-02-18

Fig. 1. Package outline SSOP24 (SOT556-1)

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3. Soldering

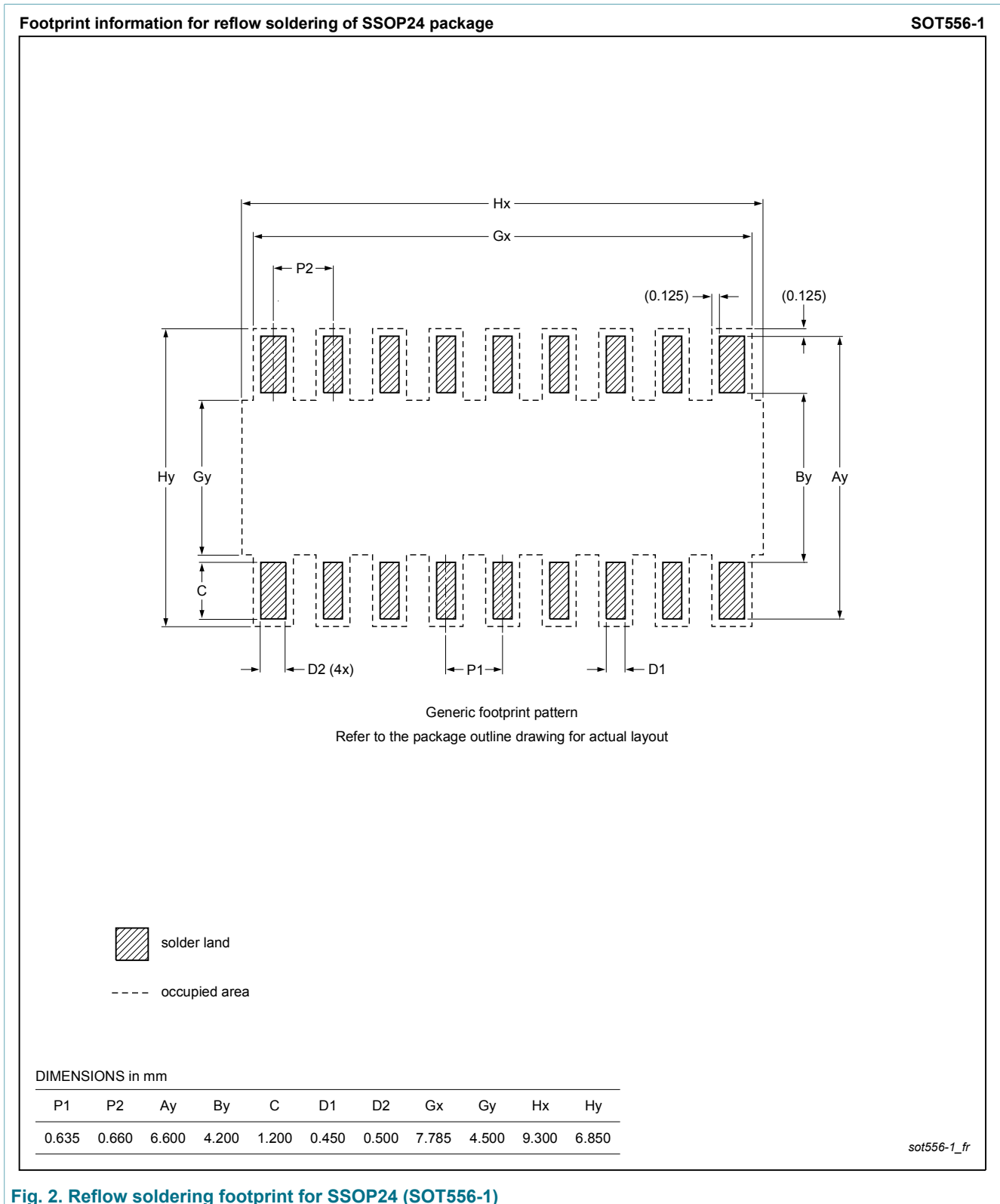


Fig. 2. Reflow soldering footprint for SSOP24 (SOT556-1)

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4. Legal information

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